

Charge collection & electric field properties of irradiated thin n-in p planar pixel sensors



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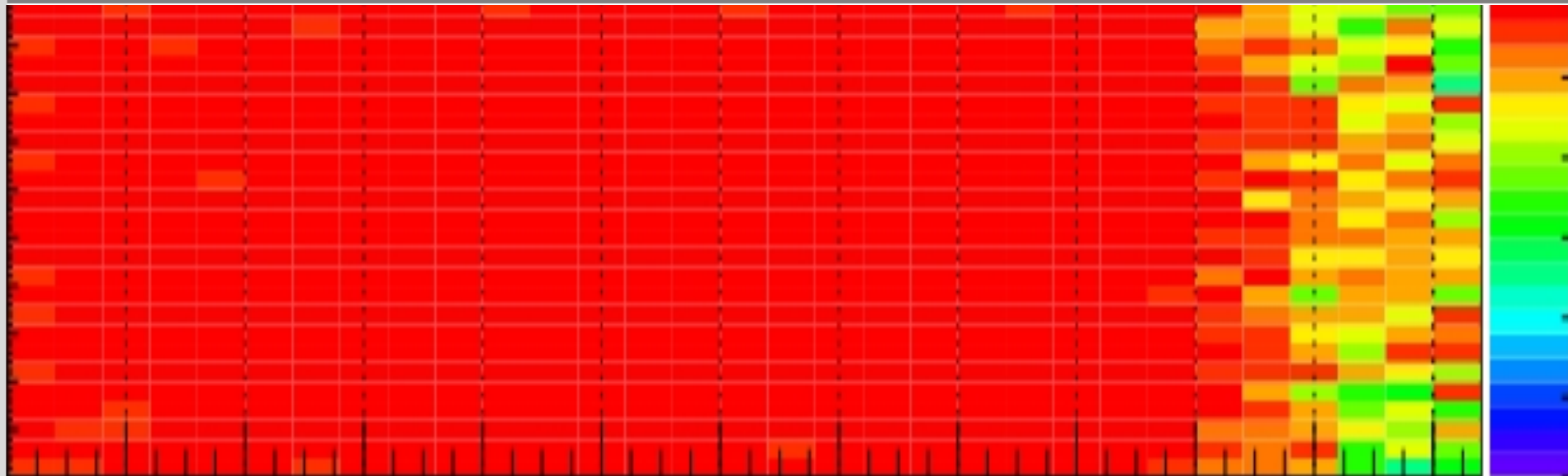
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30th RD50 Workshop, Krakow, June 5th-7th 2017

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> **Charge collection of CIS n-in-p pixel sensors**

- i. TCT studies with (un-)irradiated sensors with a thicknesses of 100 and 150 μm
- i. Irradiation level up to $1 \times 10^{16} \text{ n}_{\text{eq}}/\text{cm}^2$
- ii. Standard $50 \times 250 \mu\text{m}^2$ pixel cell and $50 \times 50 \mu\text{m}^2$ pixel implants
- ii. Comparison to source scan and test beam measurements

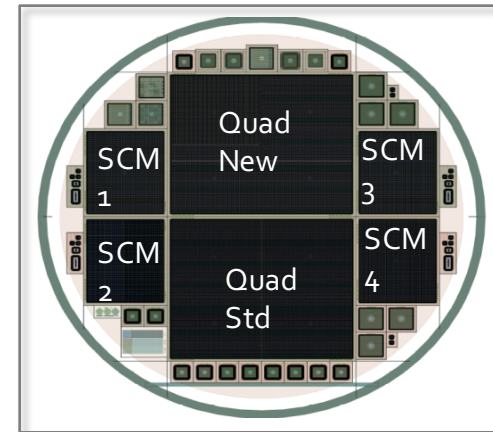
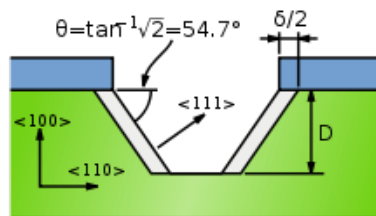
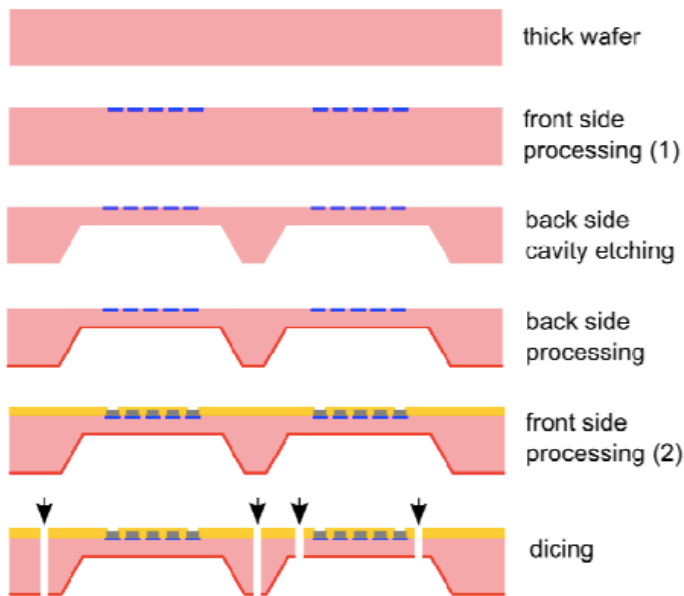
> **Electric field properties of CIS n-in-p pixel sensors**

CIS Production



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- Thin production on 4" wafers for 100 and 150 μm thick sensors
- Thinning technology without using support/handling wafer by anisotropic wet etching (KOH)

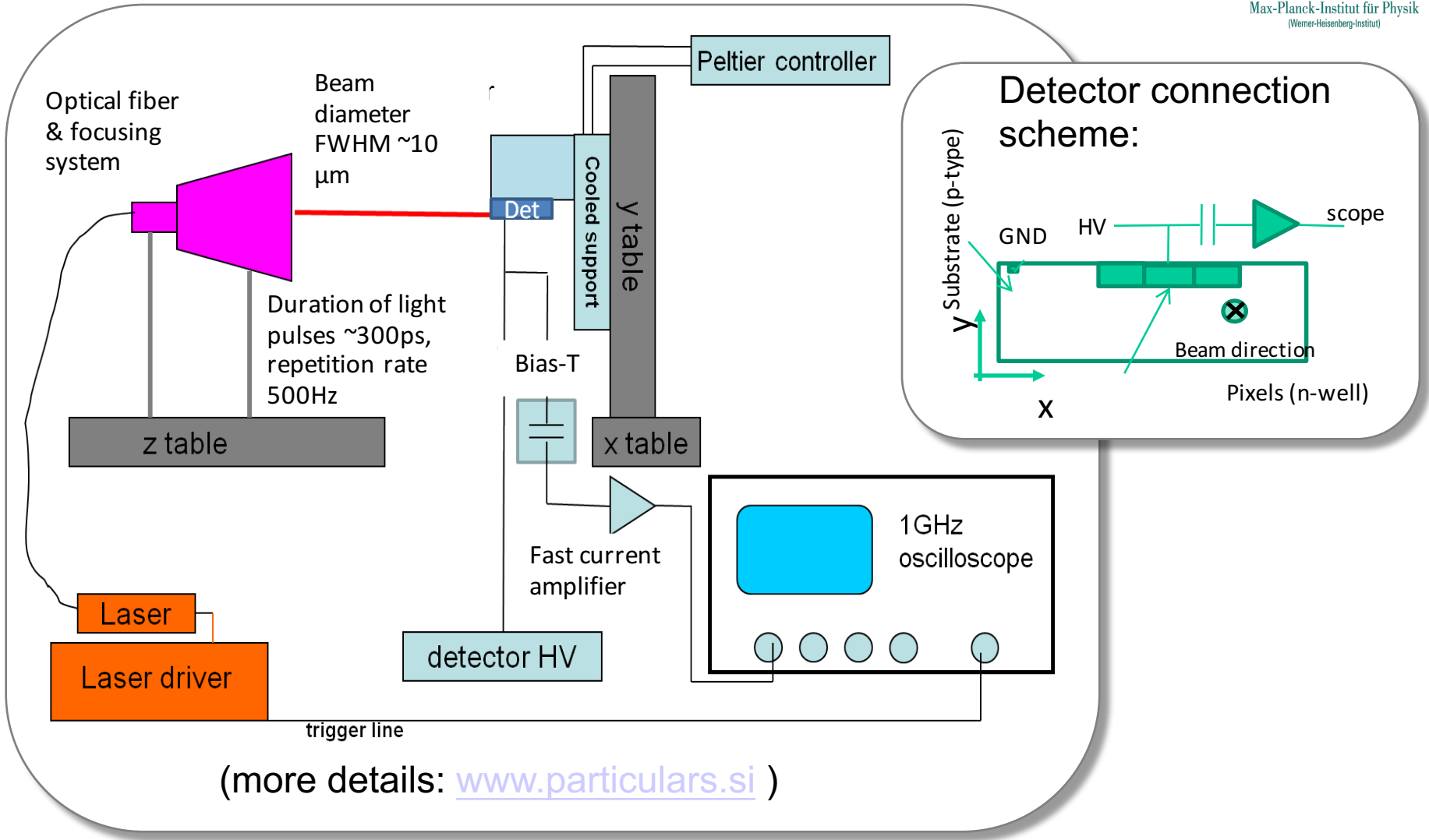


- > **CiS4** standard FE-I4 pitch
 - Pixel size : $50 \times 250 \mu\text{m}^2$
 - Pixel matrix : 80×336
- > **CiS4** with $50 \times 50 \mu\text{m}^2$ implants
 - Pixel size : $50 \times 250 \mu\text{m}^2$
 - Pixel matrix : 80×336

Edge-TCT: The measurement set-up



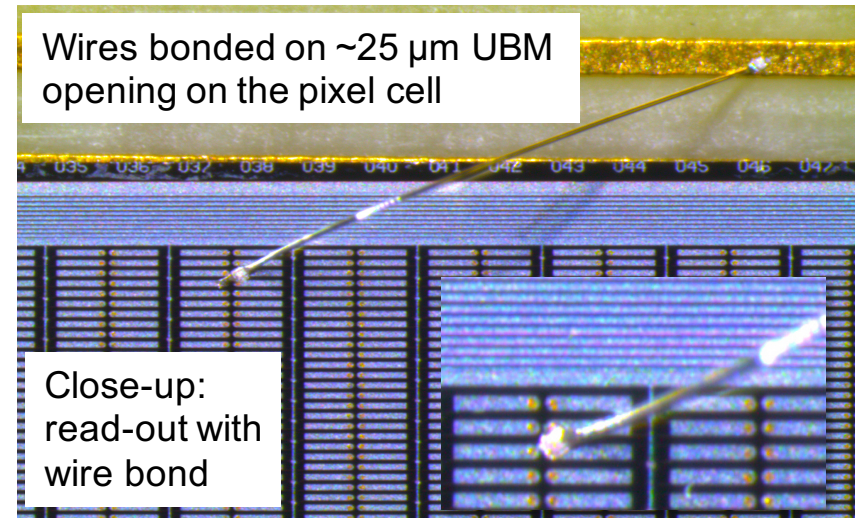
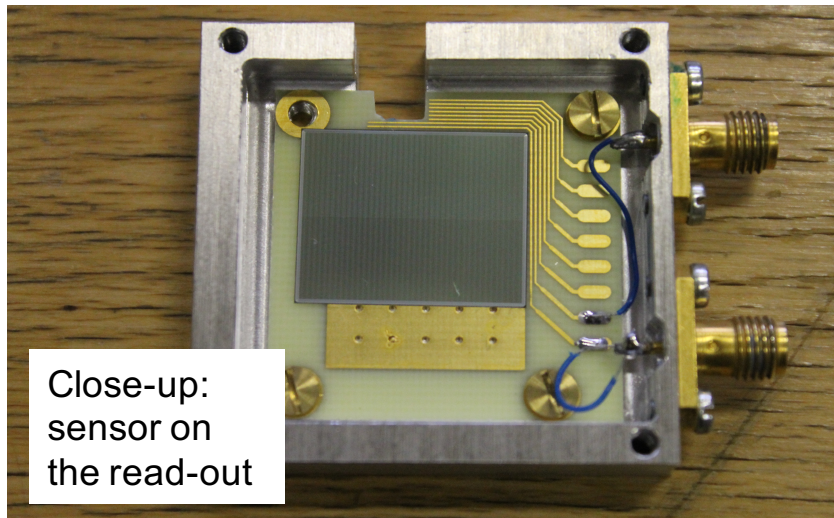
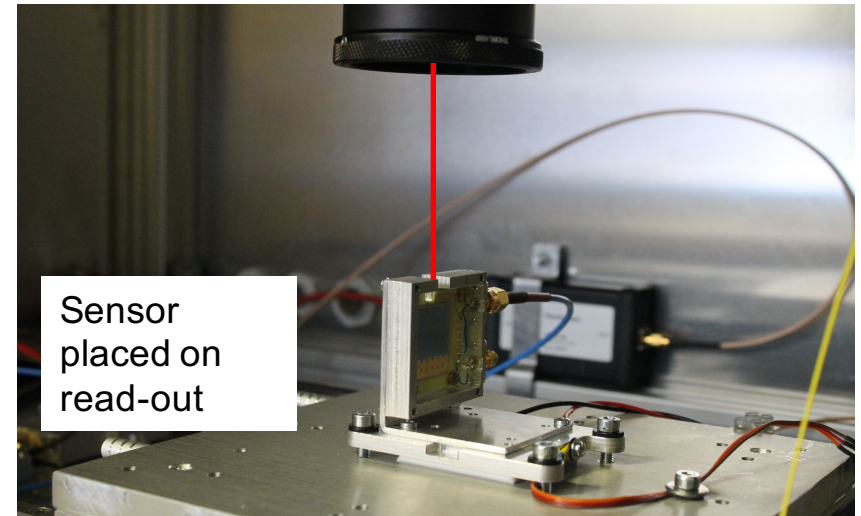
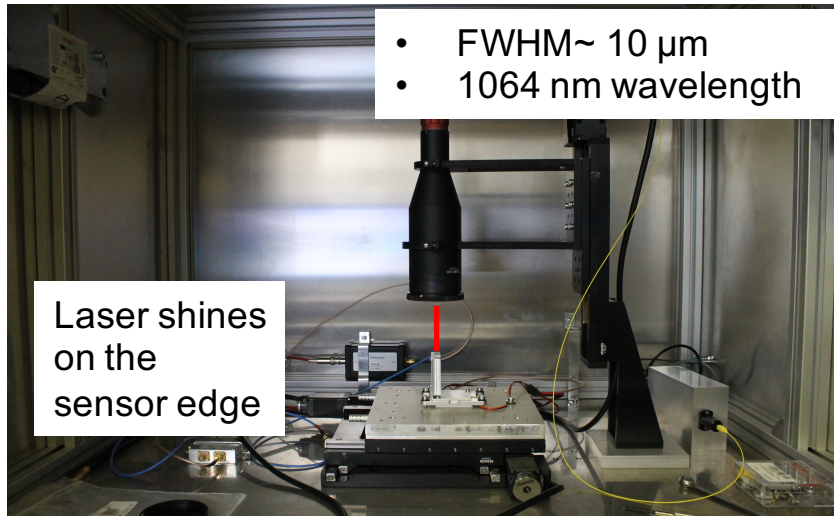
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Edge-TCT: The measurement set-up



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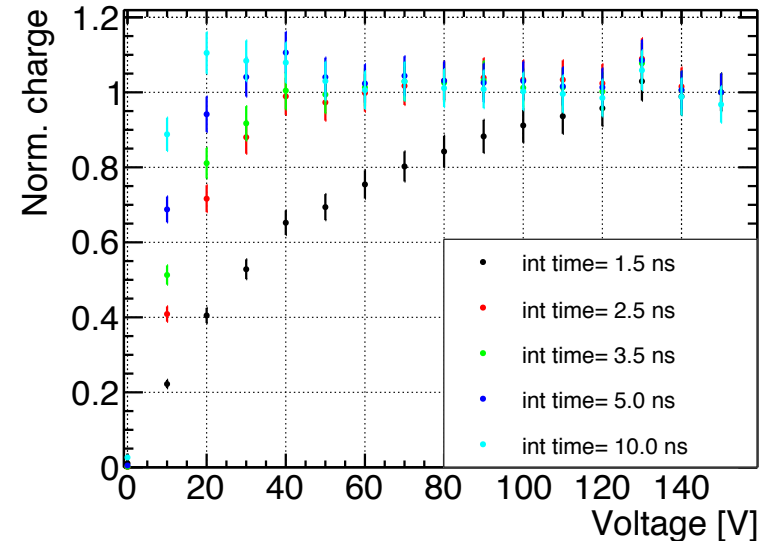
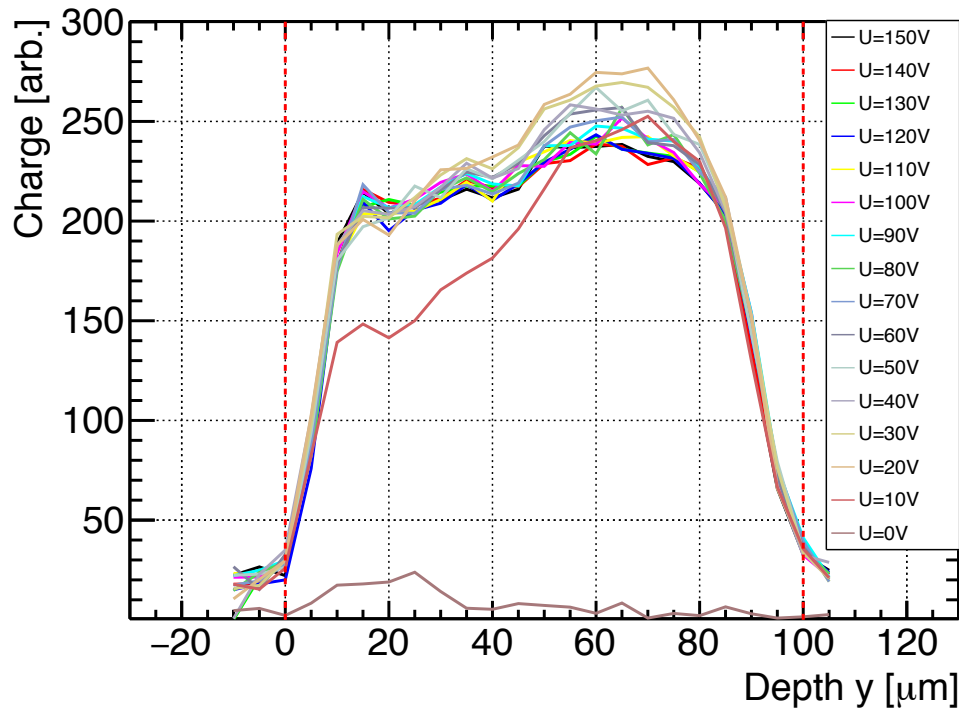
Results of a standard 50x250 μm^2 pixel cell in 100 and 150 μm thick sensors

Charge vs depth at no irradiation



100 μm

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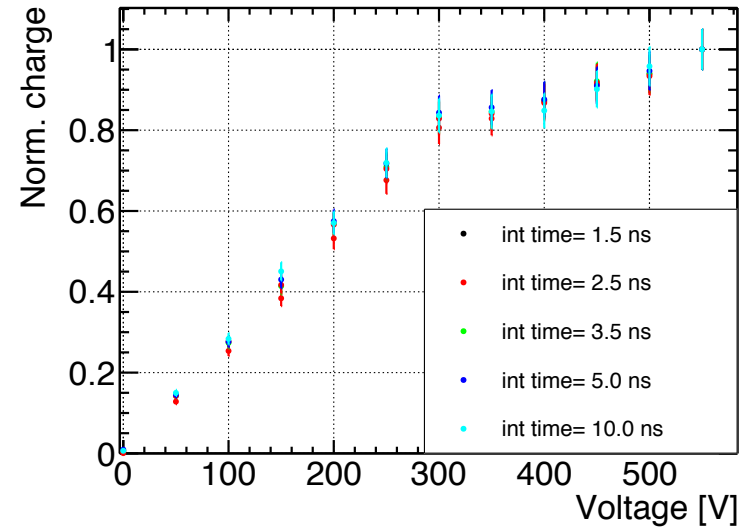
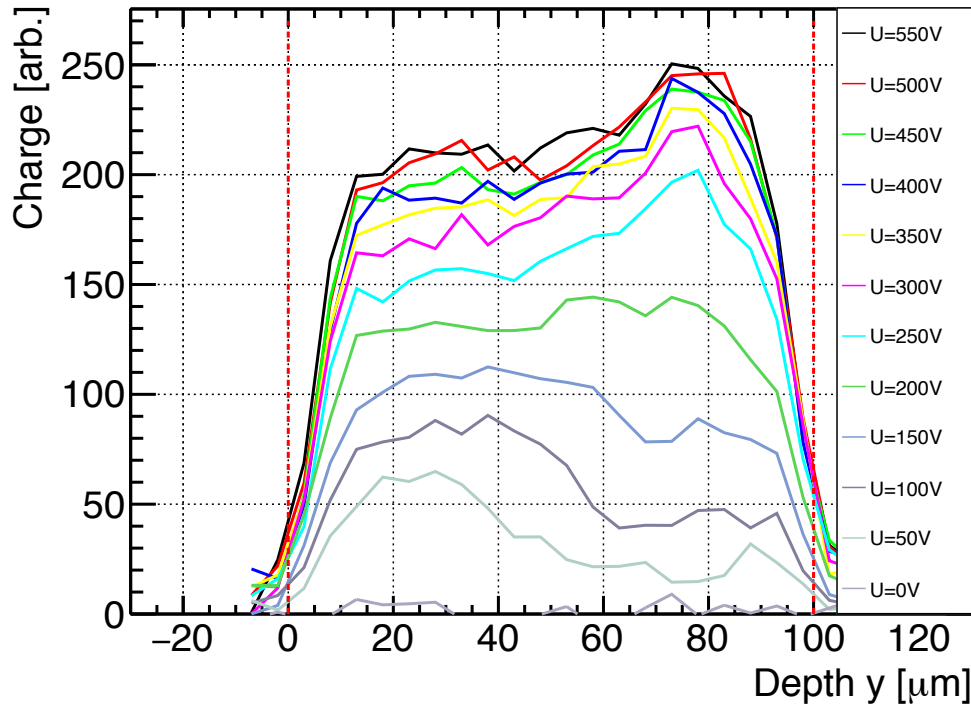


- Depletion voltage of around 20V fits well to expectations
- Depletion voltage changes artificially with integration time
 - Integration time $t=10\text{ns}$ is chosen to be the most appropriate one

not irradiated

Charge vs depth at $5 \times 10^{15} \text{ n}_{\text{neq}}/\text{cm}^2$

100 μm

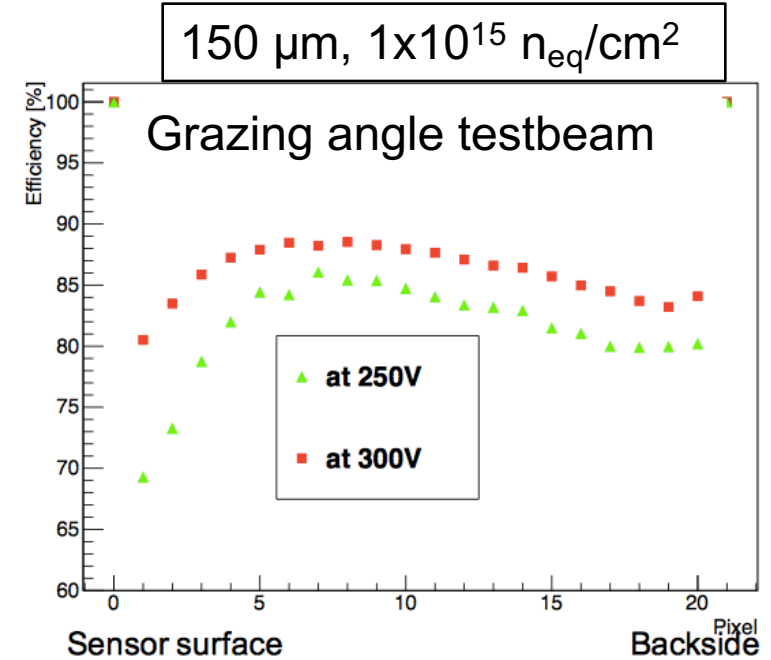
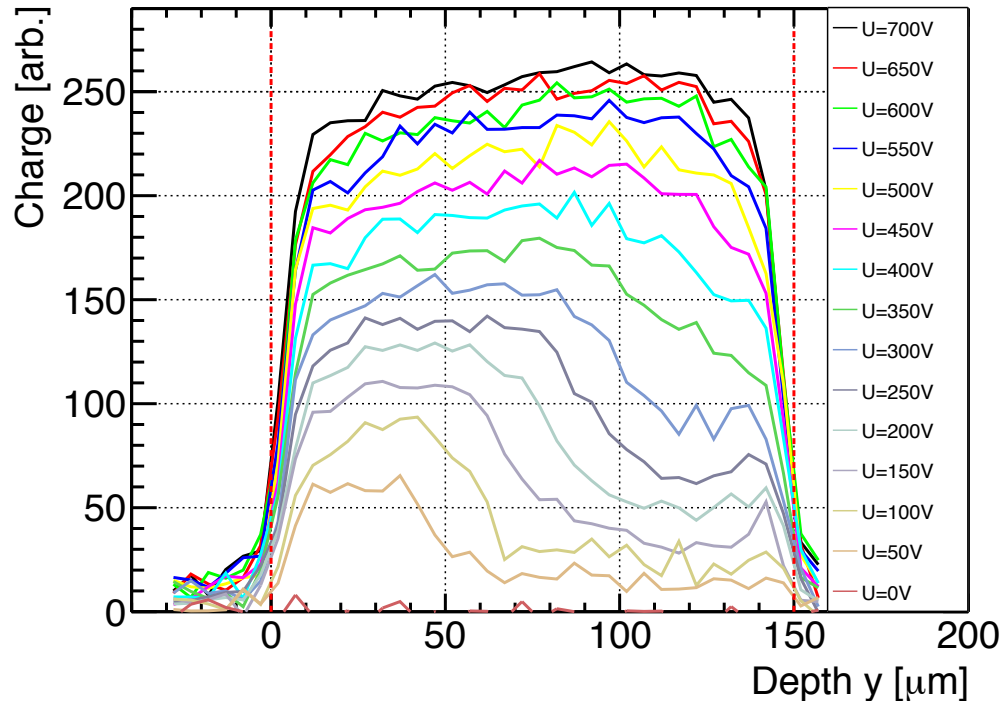


- Depletion voltage around 300V is in agreement with data from test beam measurements
- Comparison of different integration times shows similar charge collection behaviour

Irradiated to
 $5 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$

Charge vs depth at $5 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$

150 μm

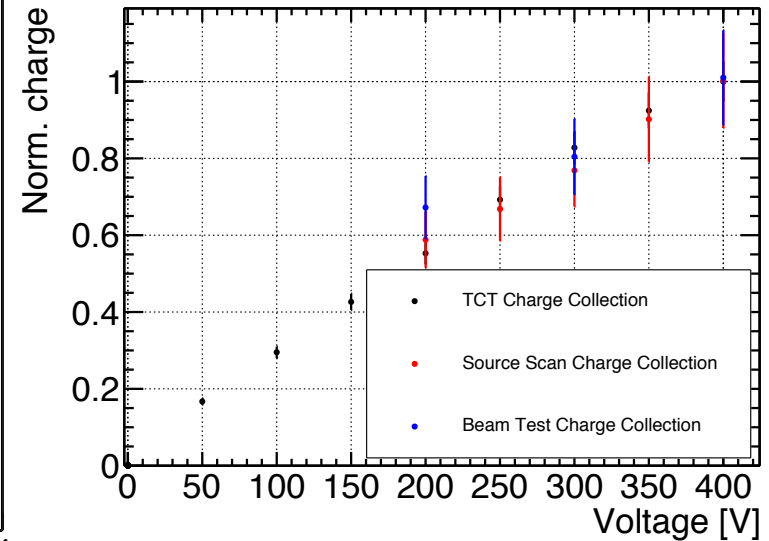
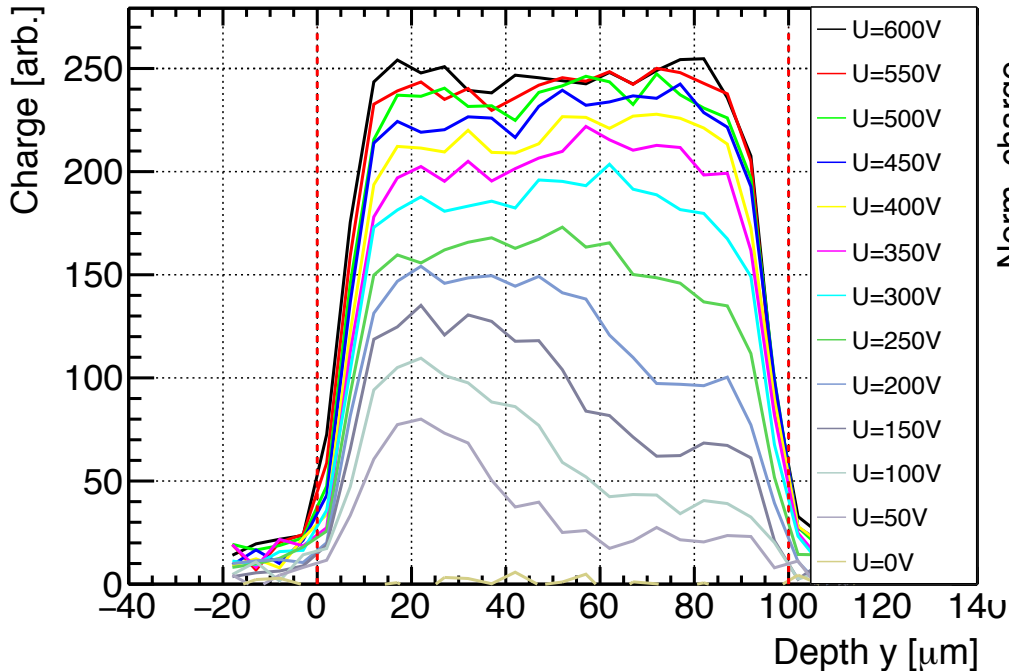


- Depletion around 500V (from the charge profile)
- Depletion voltage agree with test beam measurements
- Double peak also visible in test beam measurements at high incidence angle

Irradiated to
 $5 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$

Charge vs depth $1 \times 10^{16} \text{ n}_{\text{eq}}/\text{cm}^2$

100 μm



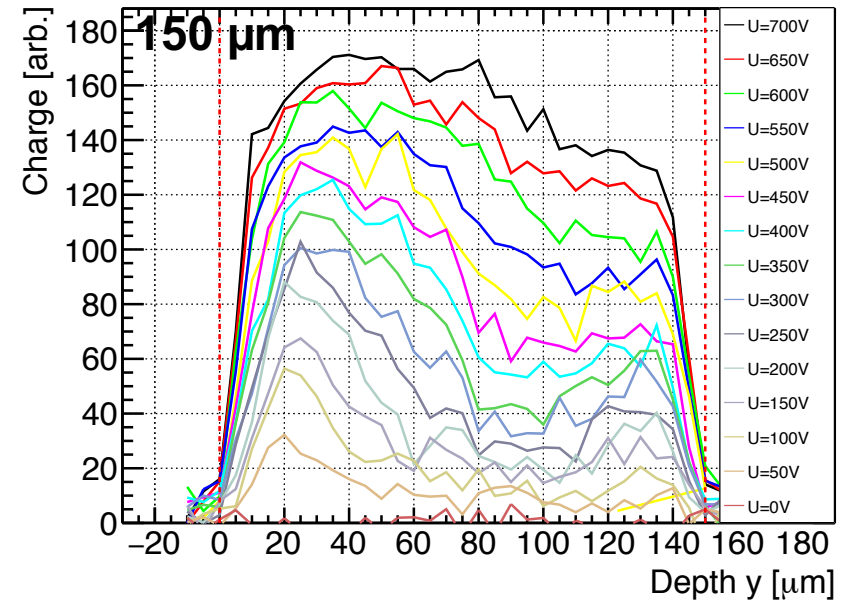
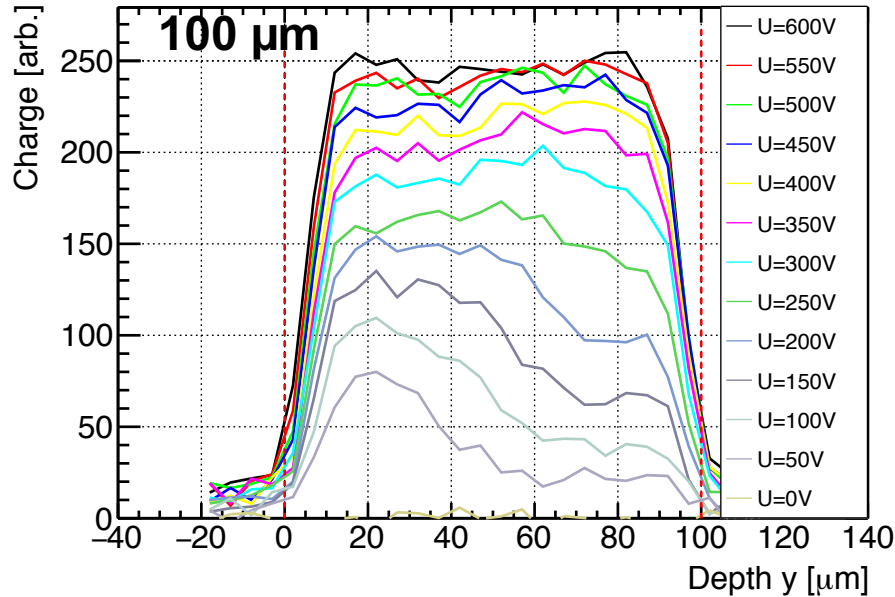
- Depletion voltage around 450V
- Flat charge collection throughout the sensor at higher voltages
- Comparison of normalized charge values of TCT, source scan and test beam measurements shows similar charge collection behaviour

**Irradiated to
 $1 \times 10^{16} \text{ n}_{\text{eq}}/\text{cm}^2$**

Charge vs depth $1 \times 10^{16} \text{ n}_{\text{eq}}/\text{cm}^2$



100 and 150 μm



- Comparison of charge collection of 100 and 150 μm thick sensors
- 150 μm thick sensor is not fully depleted at 700V, but higher voltages were not possible due to high currents
- Depletion voltage is around 800-900V (taken from test beam results)

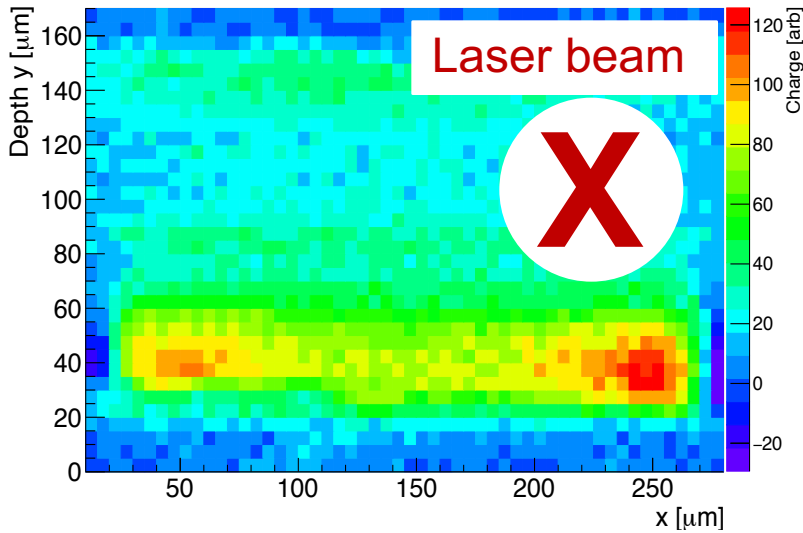
Irradiated to
 $1 \times 10^{16} \text{ n}_{\text{eq}}/\text{cm}^2$

2D Charge profile

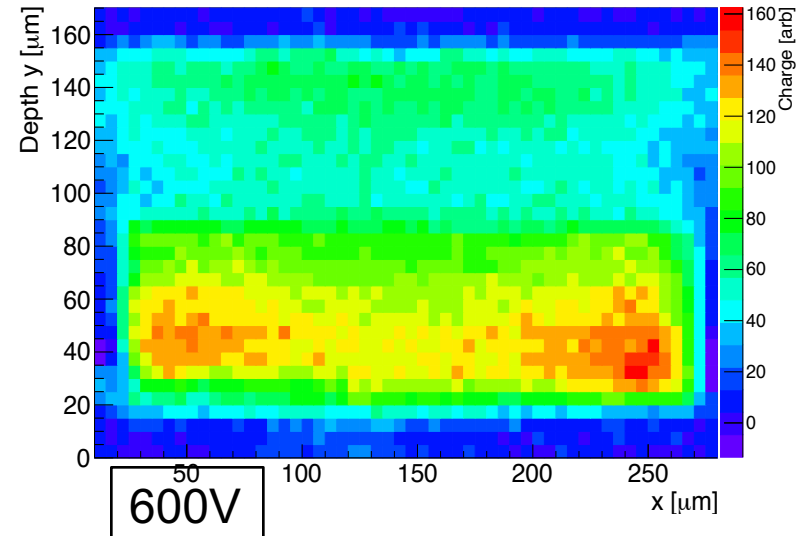


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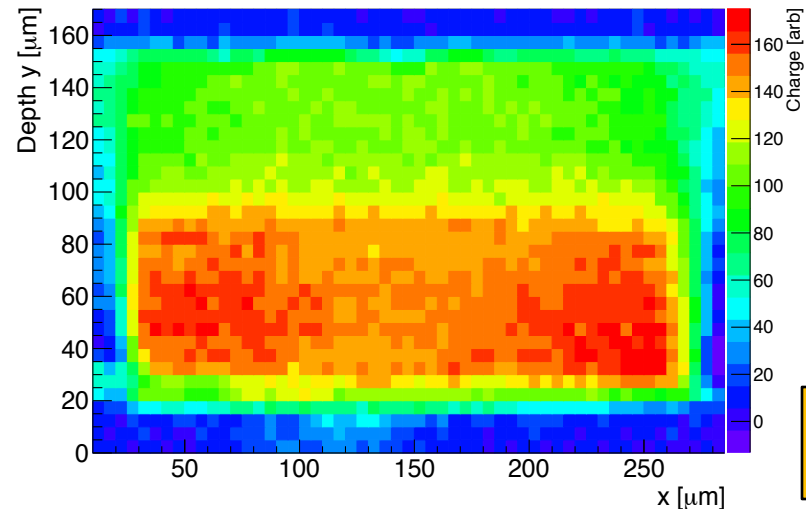
200V



150 μm
400V



600V



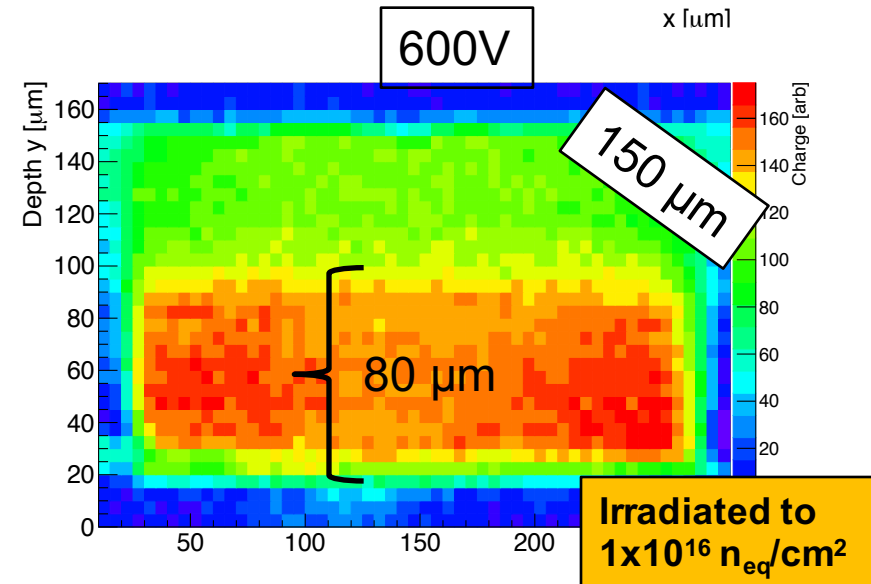
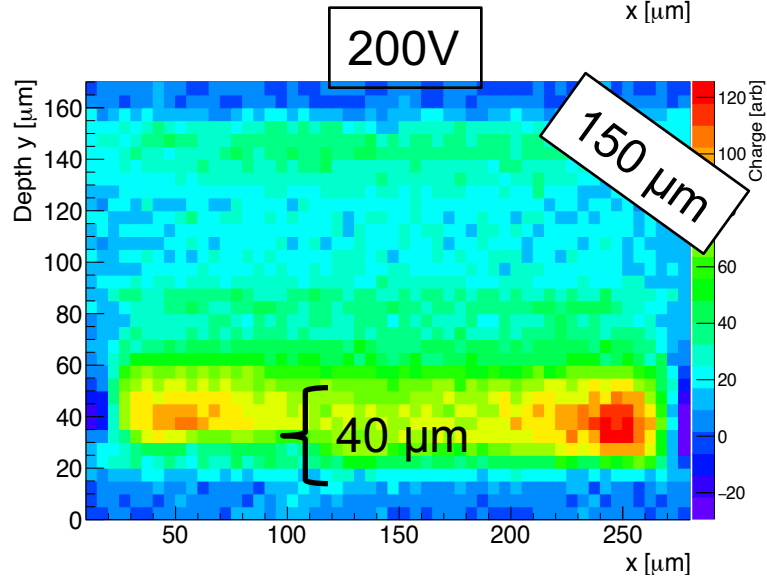
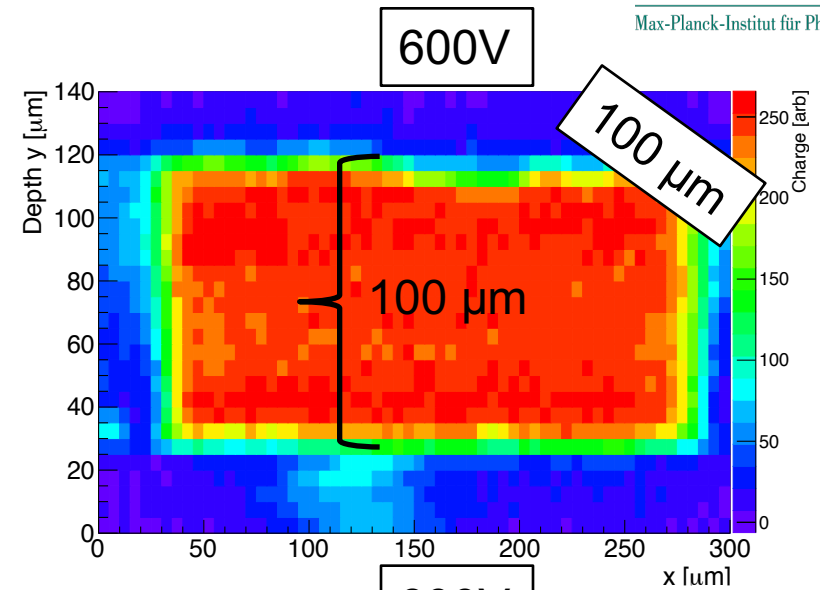
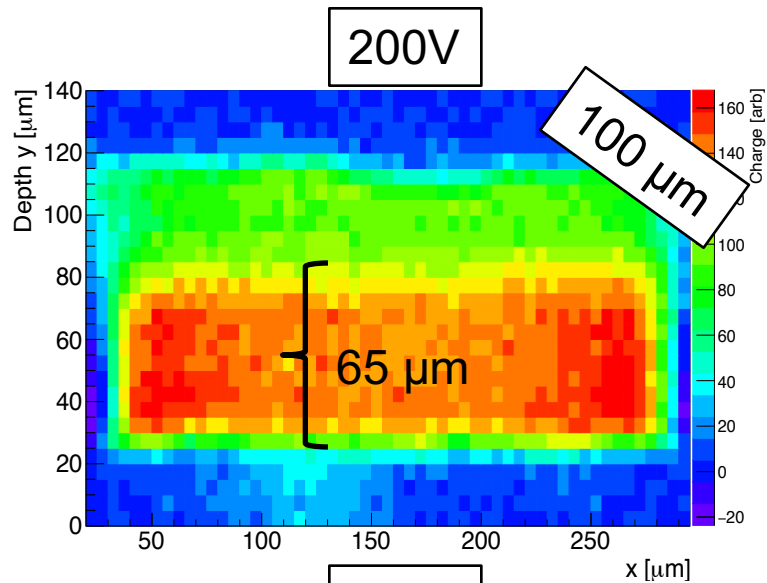
Irradiated to
 $1 \times 10^{16} \text{ n}_{\text{eq}}/\text{cm}^2$

Sensor front side with
Pixel size in x = 250 μm

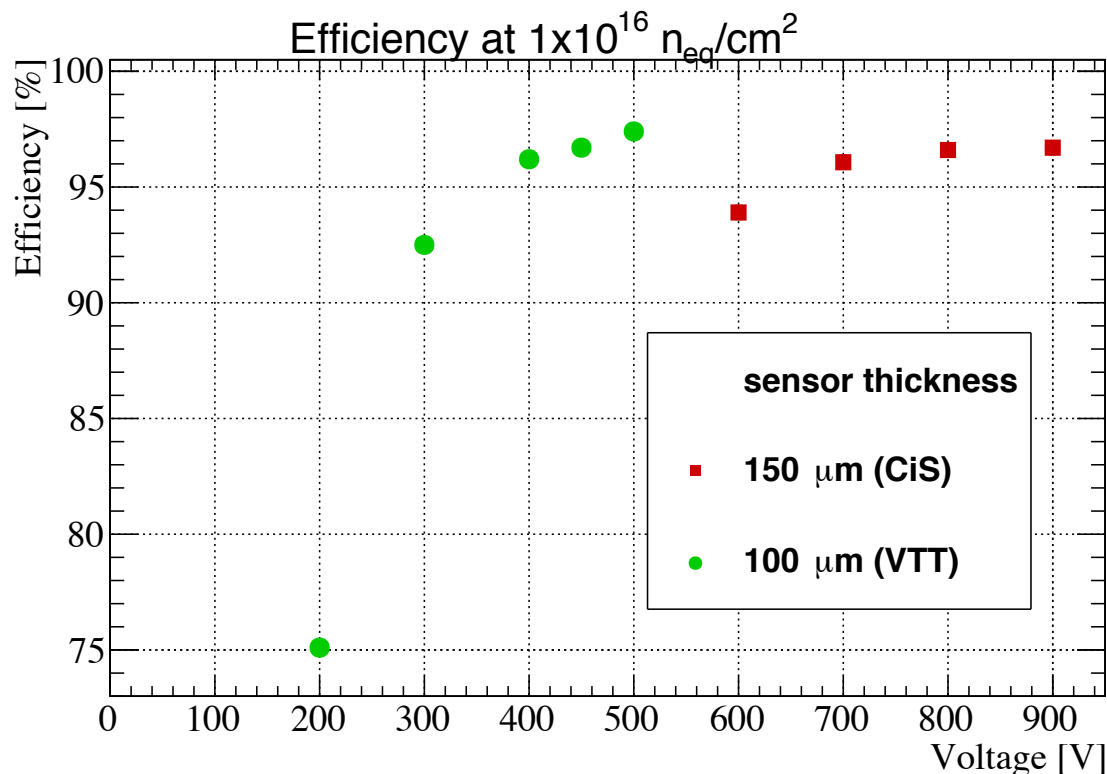
Depletion regions in 100 and 150 μm



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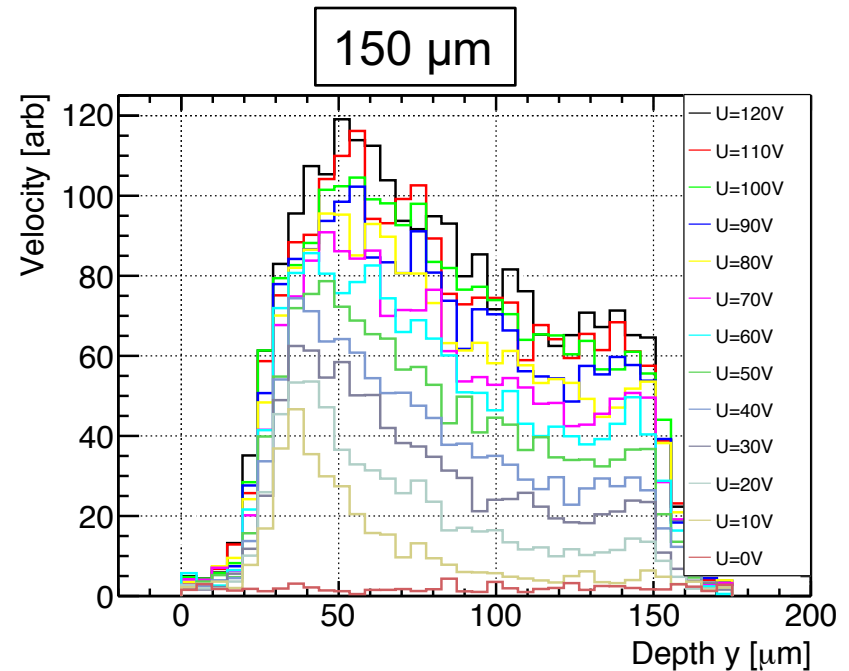
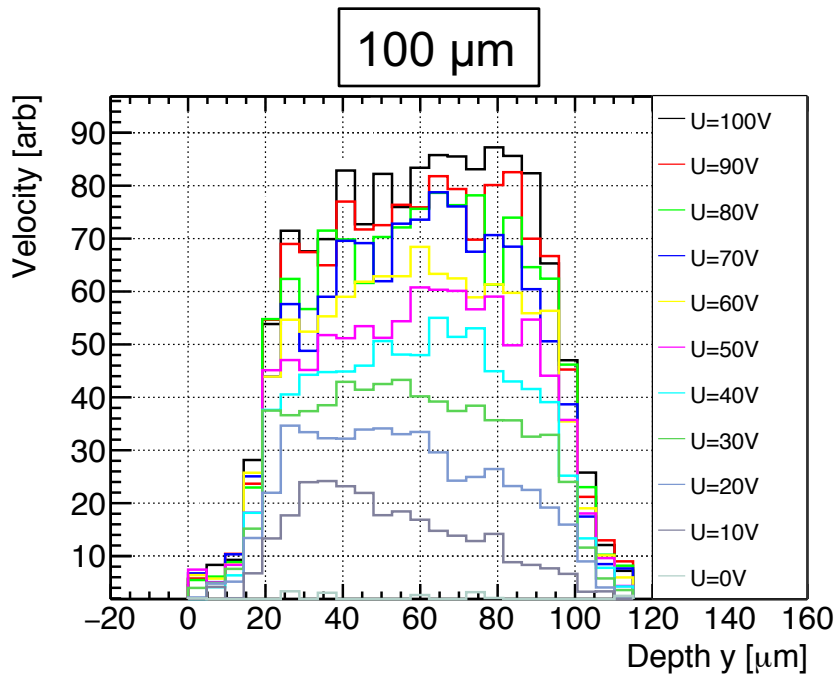
Hit efficiency of 100 and 150 μm thick sensors



- Comparison of hit efficiencies shows a higher hit efficiency for the module with a 100 μm thick sensor compared to the module with the 150 μm thick sensor
- Results support the charge collection results obtained from the TCT measurements

Irradiated to
 $1 \times 10^{16} \text{ n}_{\text{eq}}/\text{cm}^2$

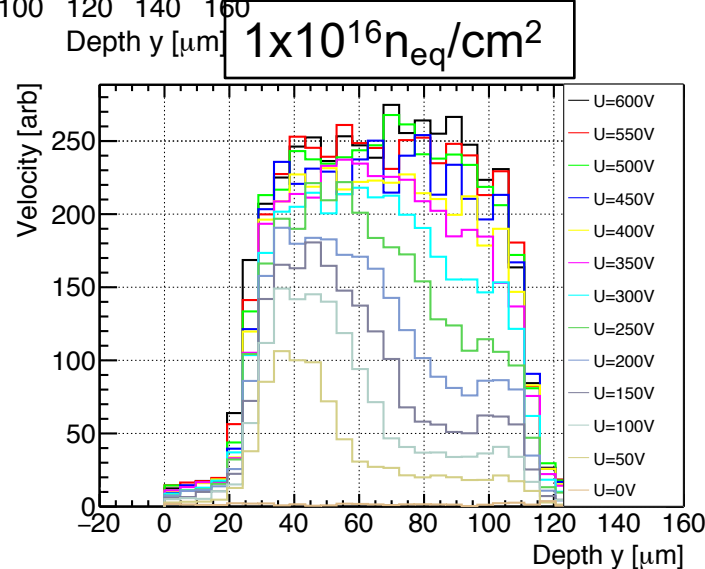
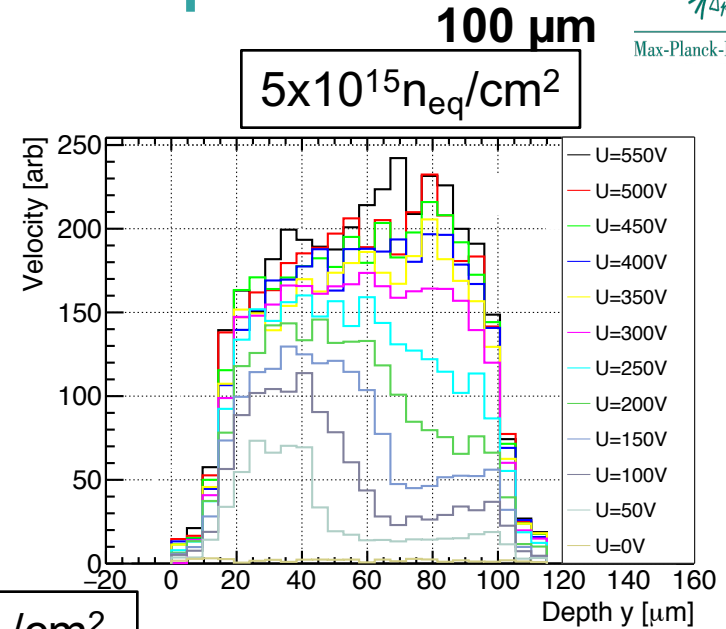
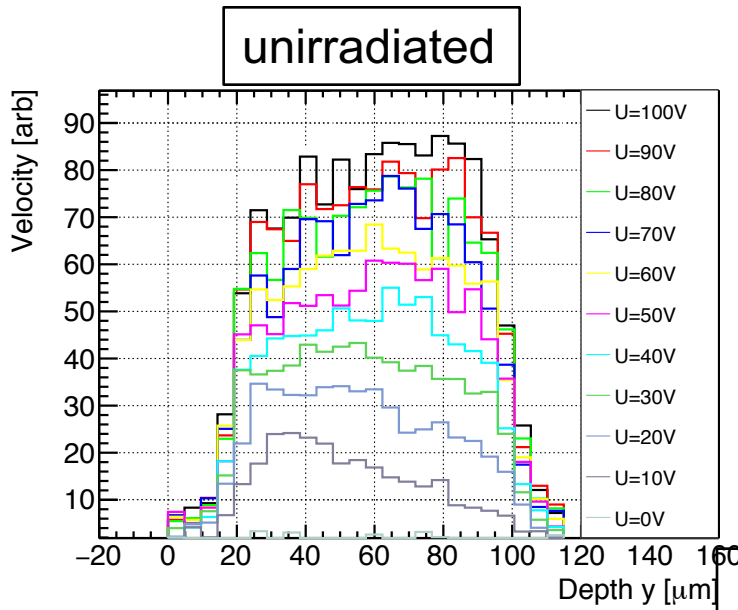
Velocity profiles for 100 and 150 μm



- Velocity profile does not get flat for a 150 μm thick sensor (in line with literature)
- Electric field of 100 μm thick sensor more uniform which is visible in the saturation of the velocity of the charge carriers

not irradiated

Comparison velocity profiles for 100 μm



Indication of double peak visible after irradiation!

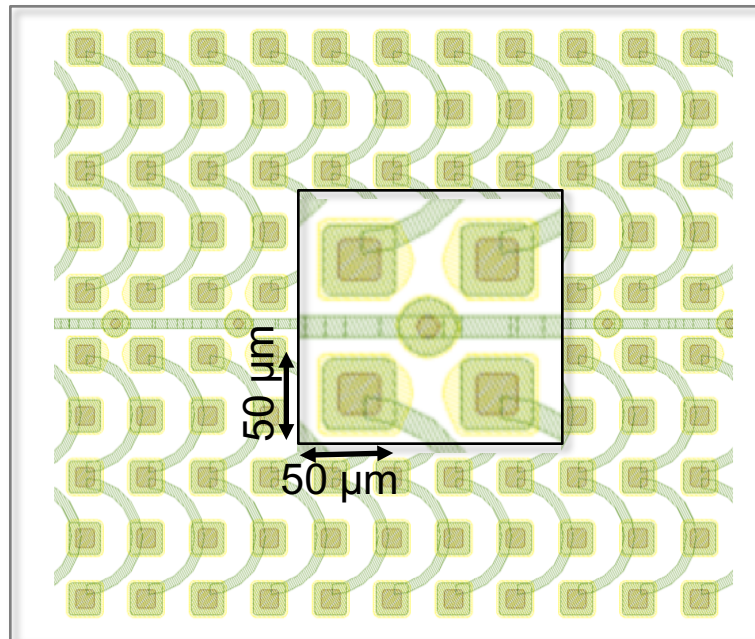


Results of a modified $50 \times 250 \mu\text{m}^2$ pixel cell with $50 \times 50 \mu\text{m}^2$ implants

CIS production

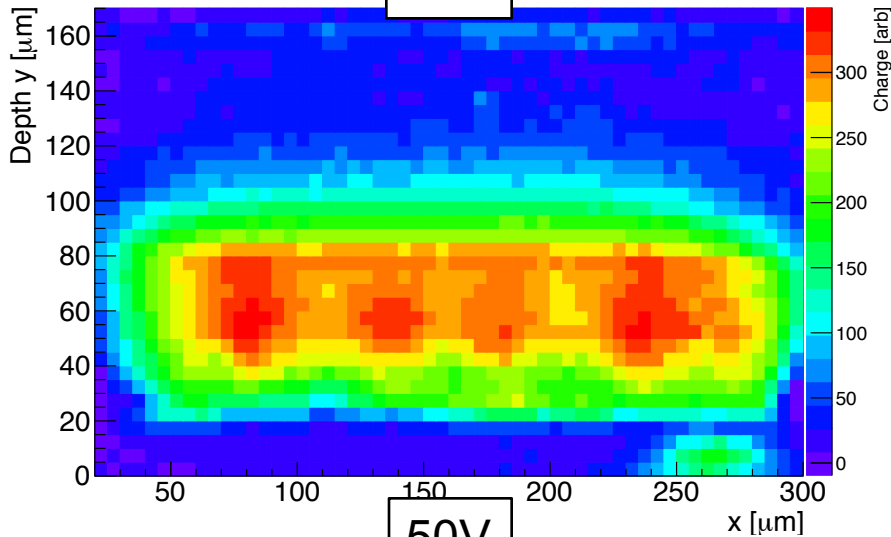


- Sensor layout with $50 \times 50 \mu\text{m}^2$ pixel implants
- 5 pixel cells of $50 \mu\text{m}$ pitch are connected with a metal rail
 - to allow for a readout with the standard FE-I4 chip with $50 \times 250 \mu\text{m}^2$ pixel cells

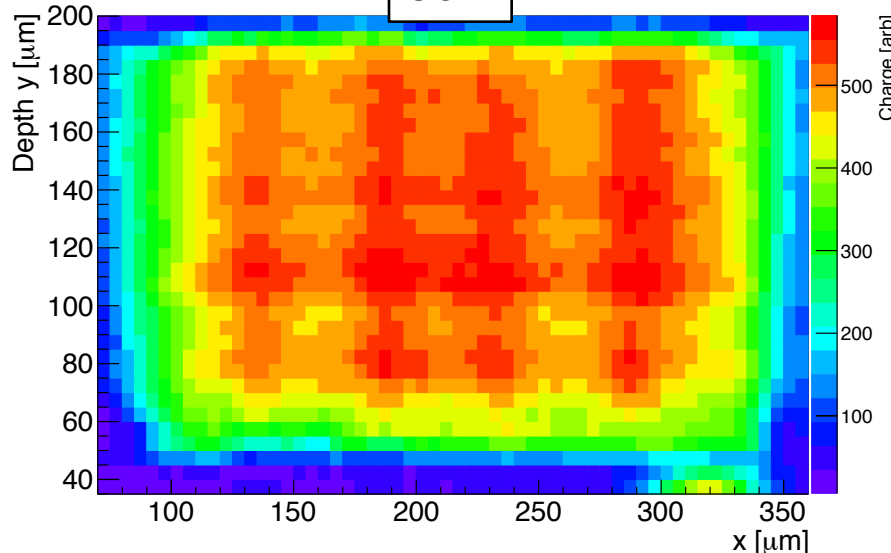


2D charge profile

10V



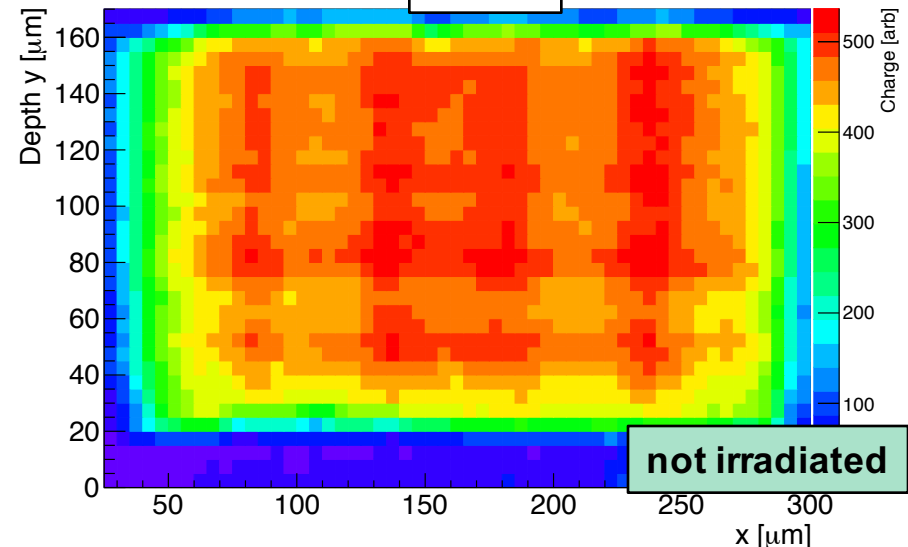
50V



150 μm

- Higher charge regions could be the inter-pixel regions
 - This could be caused by the geometry of the TCT (laser traverses the sensor parallel to the pixel cells) measurements and the modified pixel cell

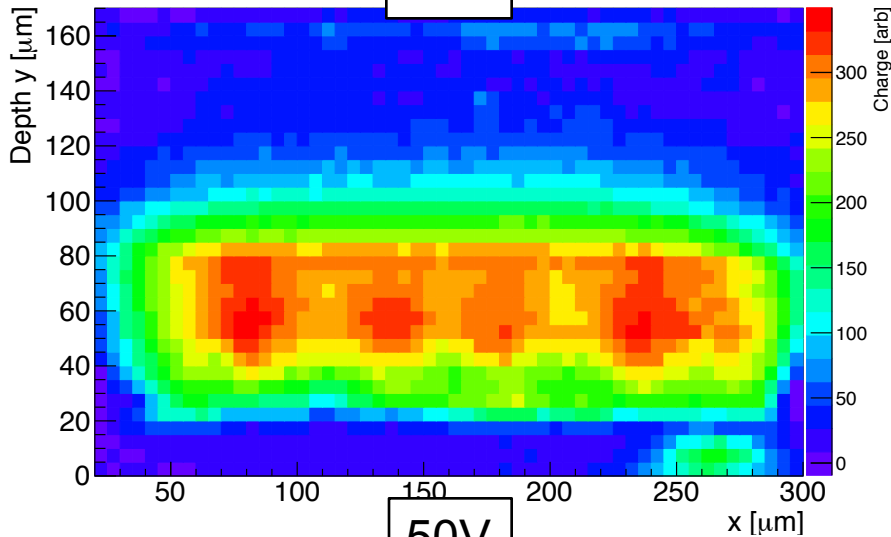
100V



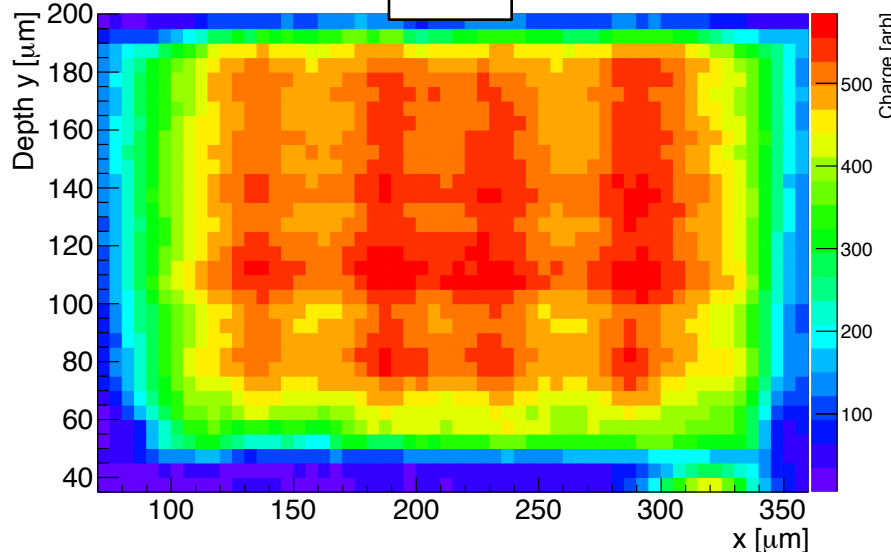
not irradiated

2D charge profile

10V



50V

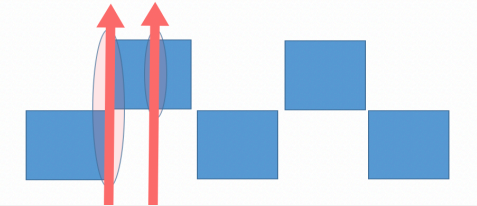


150 μm

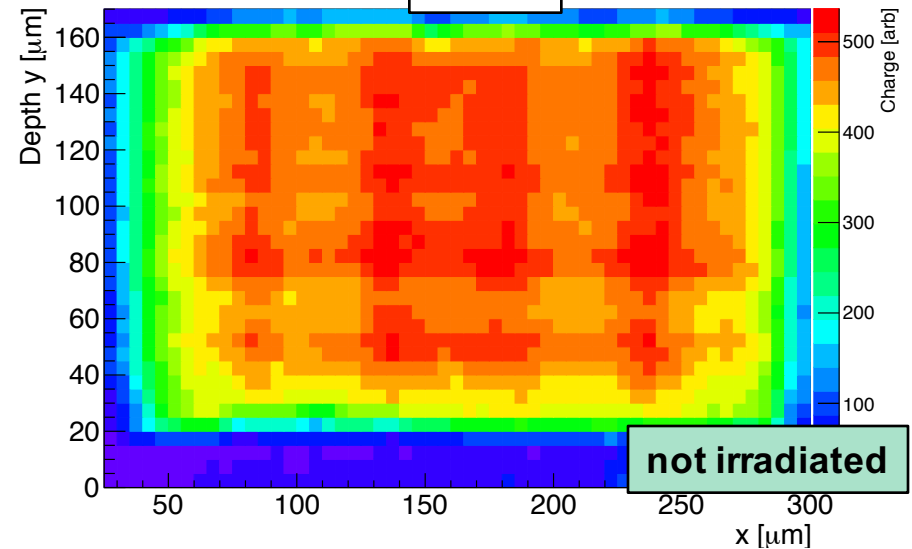


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- Charge collected from longer beam stretch could lead to higher charge collection in the inter-pixel regions because of diffusion and laser beam halo



100V



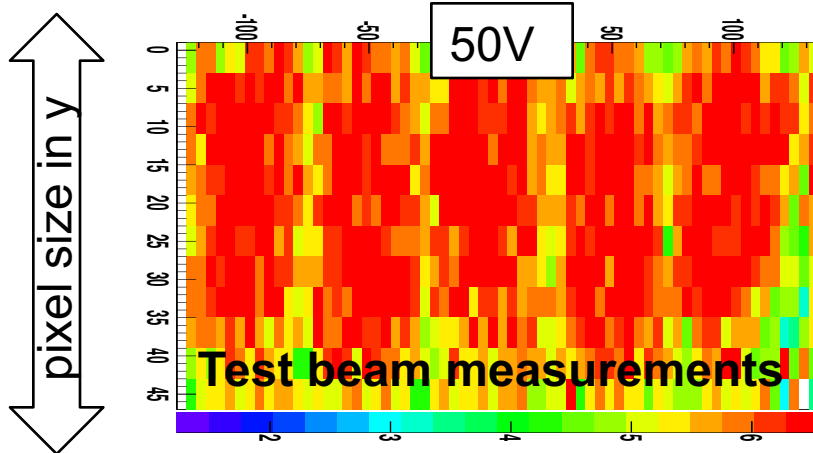
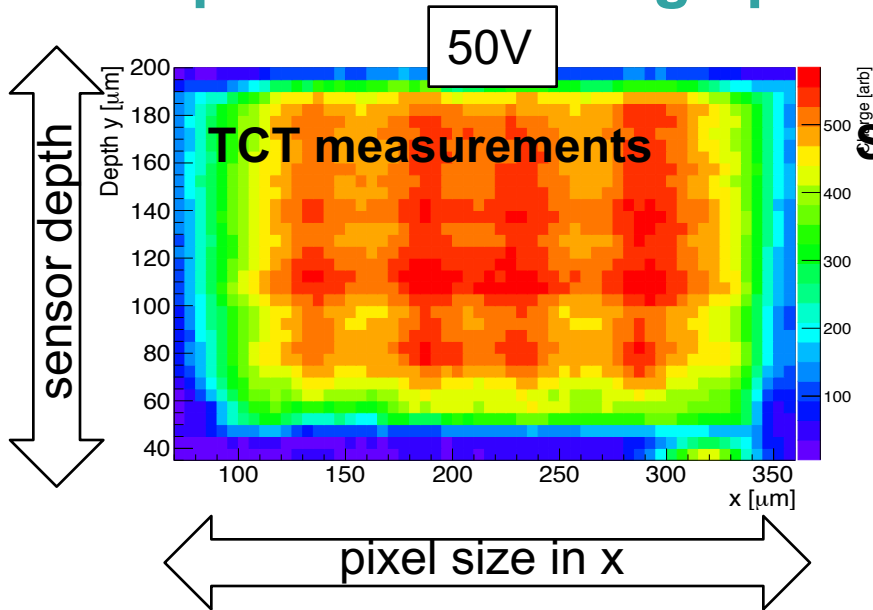
not irradiated

Comparison of charge profiles TCT and test beam



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150 μm



- The charge collection obtained by test beam measurements shows a higher charge region on the pixel implant itself
 - The beam traverses the sensors perpendicular to the pixel cells (not influenced by the geometry of the modified pixel cell)

not irradiated

- **100 μm and 150 μm thick sensors:**
 - For a 100 μm thick sensor charge collection profiles of all fluences flatten after reaching the depletion voltages
 - The 150 μm thick irradiated sensor does not reach depletion due too low voltages applied (limited by the thermal runaway)
 - Normalised charge of TCT, lab, test beam measurements are in line
 - For a 100 μm thick sensor charge carrier velocities at all fluences are maximal at the front side at lower voltages but flatten out at higher voltages (not the case for the 150 μm thick sensor)
 - Indication of double peak visible after irradiation for both thicknesses
- **50x50 μm^2 pixel implants**
 - With modified pixel design it is possible to make first prediction of the charge sharing of small pixel cells

- Confront TCT measurements with further high incidence angle test beam measurements
- Extend TCT measurements to real $50 \times 50 \mu\text{m}^2$ pixels cells (from RD53A sensors)
- Compare TCT measurements to TPA (two photon absorption) measurements



Thank you for your attention!

Special thanks to JSI, above all Igor, Bojan and Gregor!



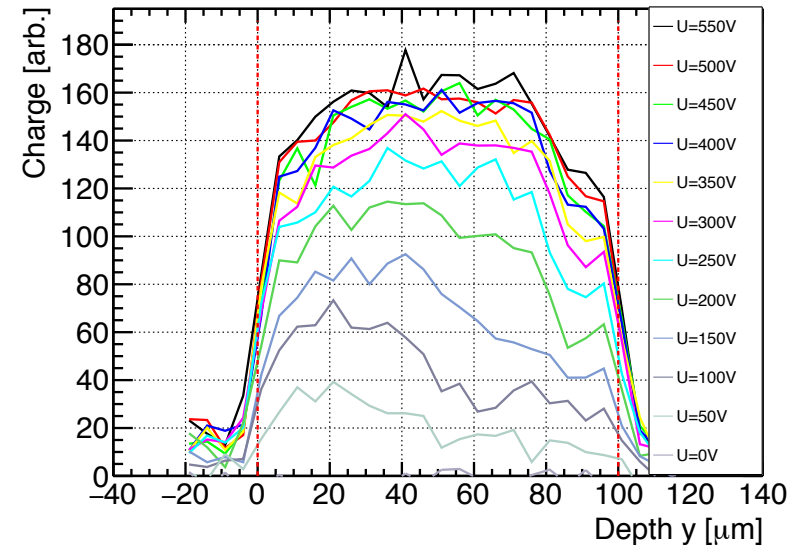
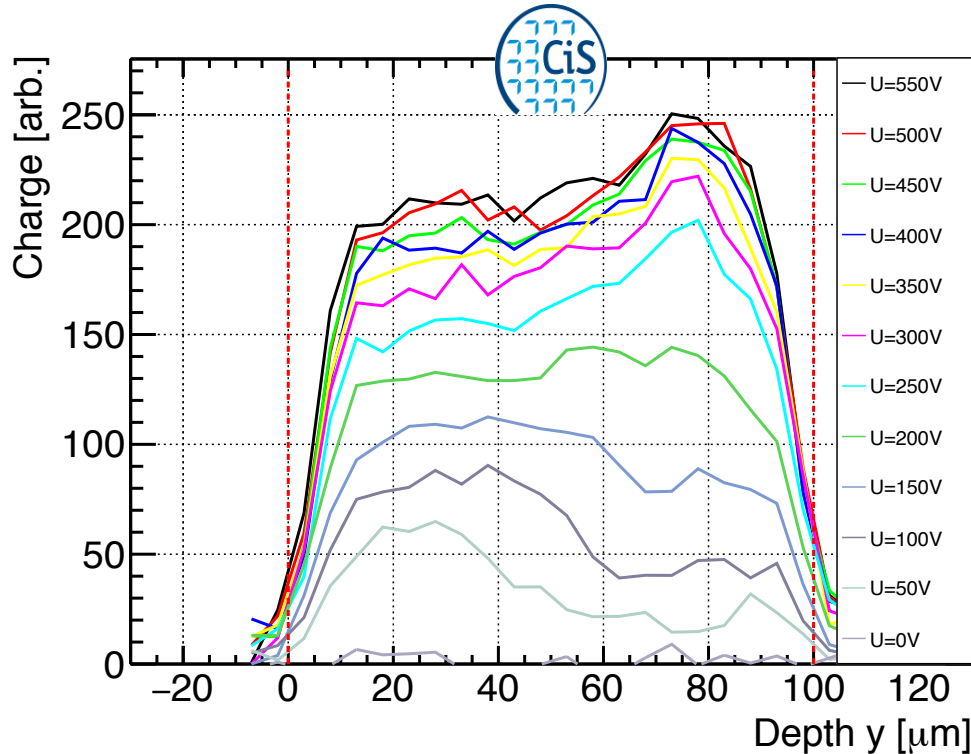
Back up

Comparison charge vs depth



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100 μm



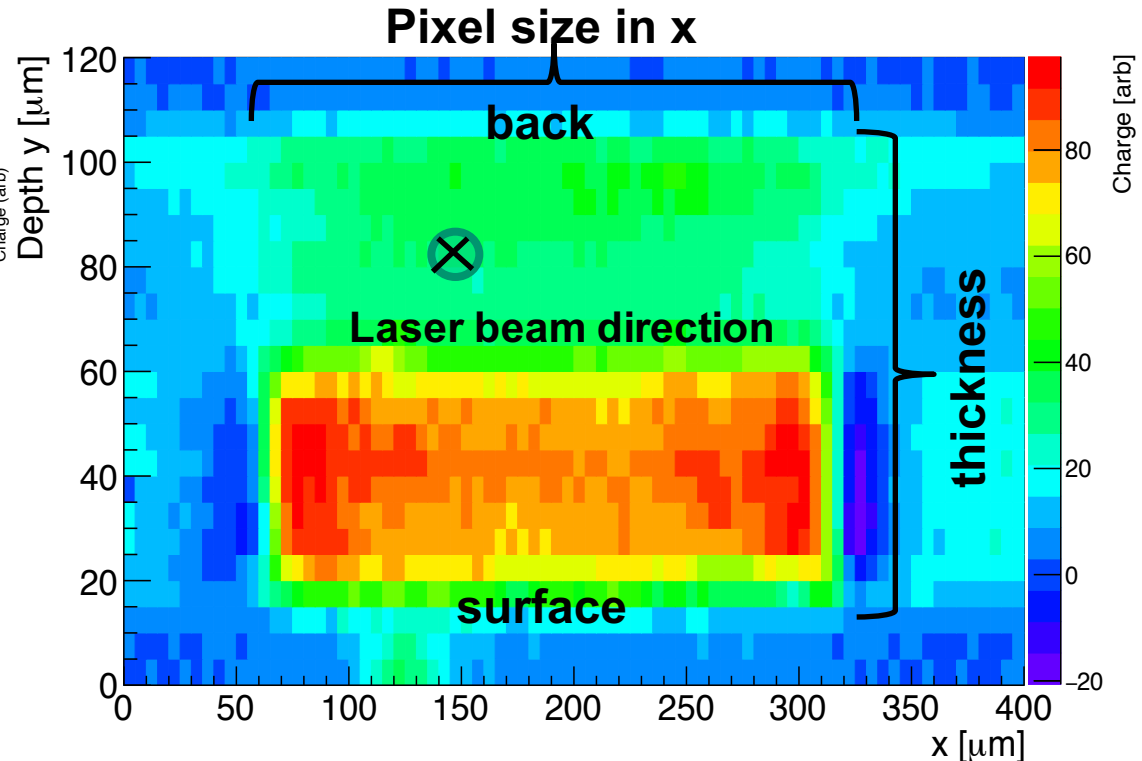
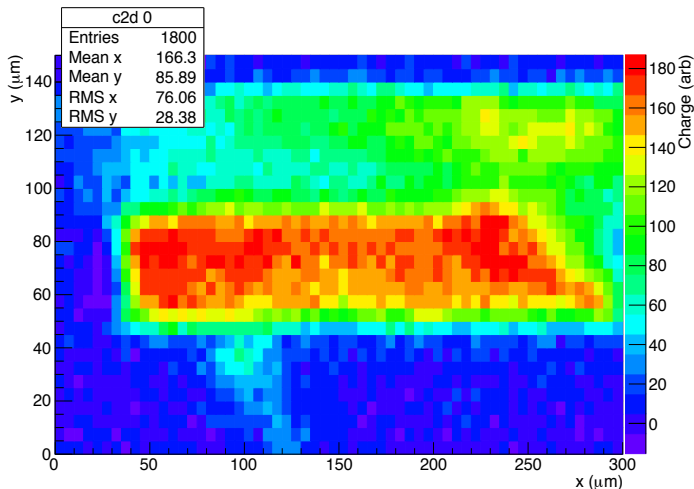
- Depletion voltage of $\sim 300\text{V}$ for both sensors
- In the 1 dimensional charge profile the lower charge in the last $10\ \mu\text{m}$ are clearly visible
- This will be checked with the charge collection scans in the lab

Irradiated to
 $5 \times 10^{15}\ \text{n}_{\text{eq}}/\text{cm}^2$

2D Charge profile two measurements

All pixels on nearly the same potential

Only read-out pixel is biased

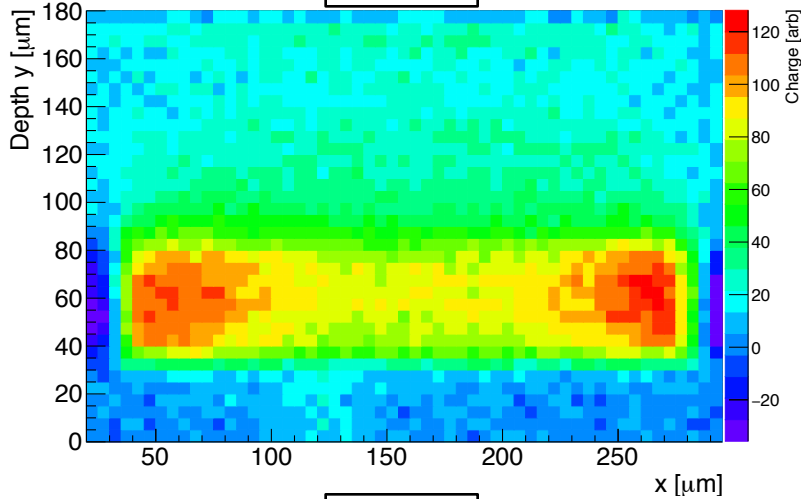


- Only read-out pixel is biased: Bias dot and rail introduce charge loss when being on a different potential
- All pixels are biased: No influence of bias dot and rail

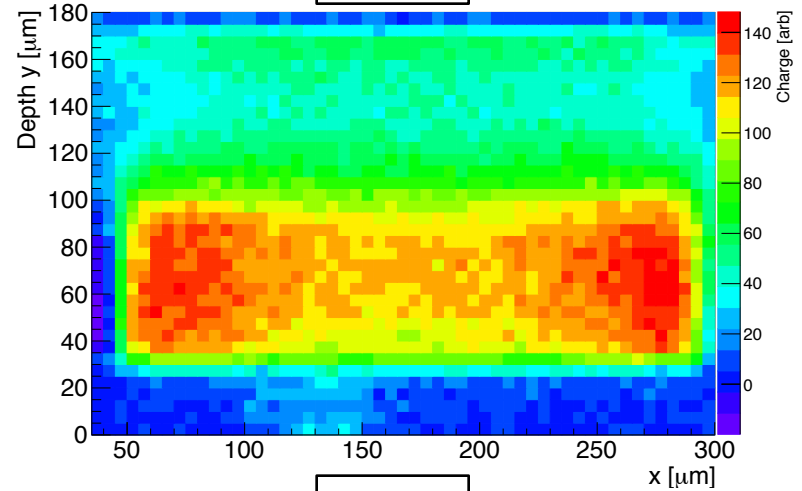
Irradiated to $5 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$

2D-Charge profile

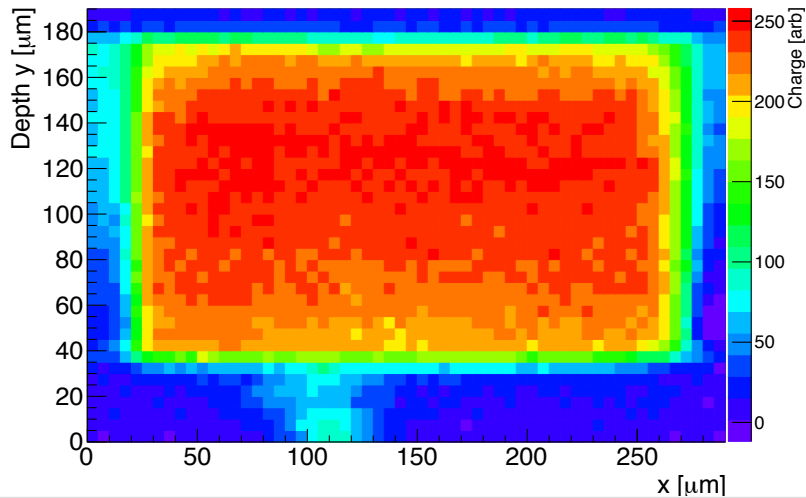
100V



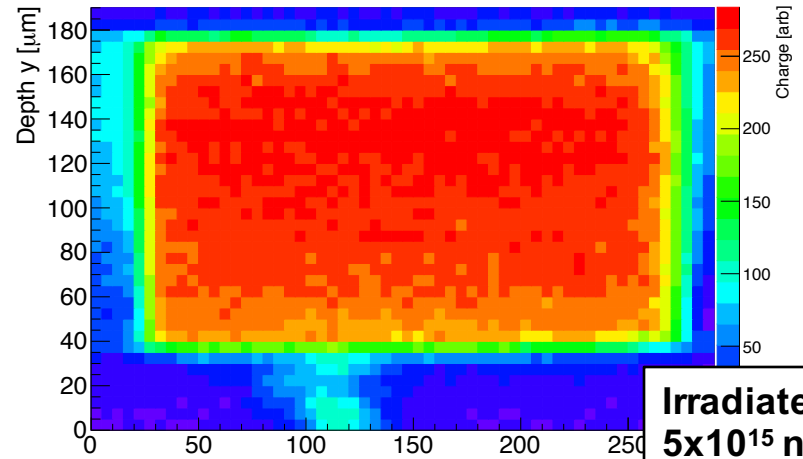
200V



600V



780V

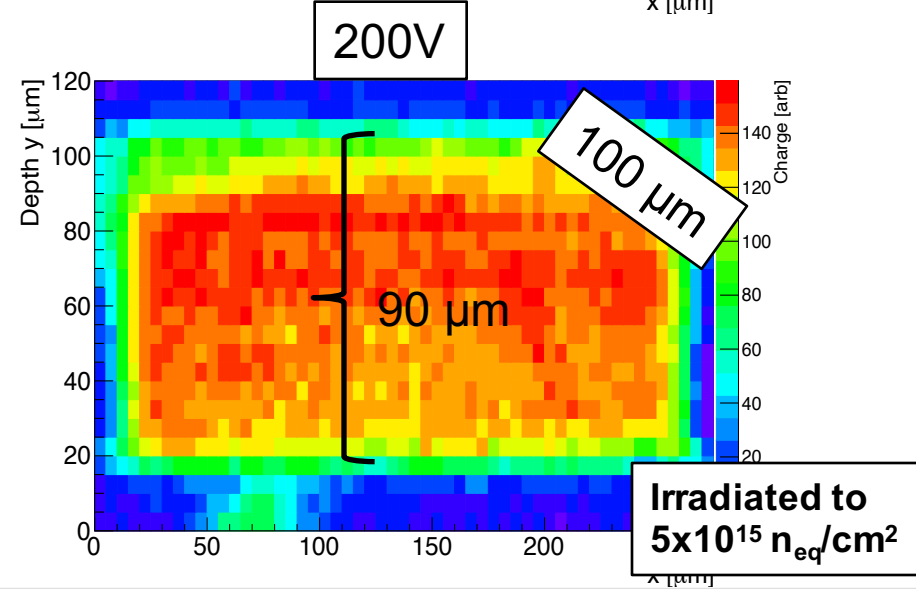
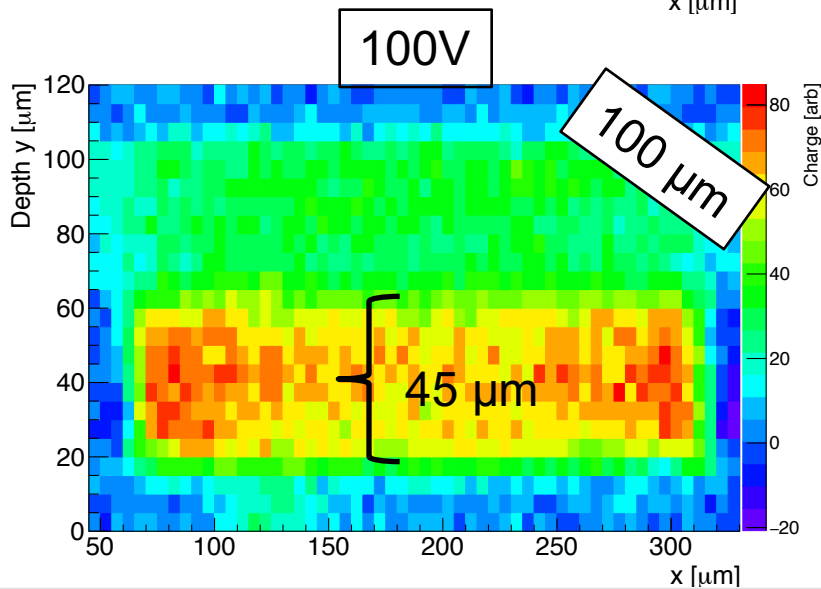
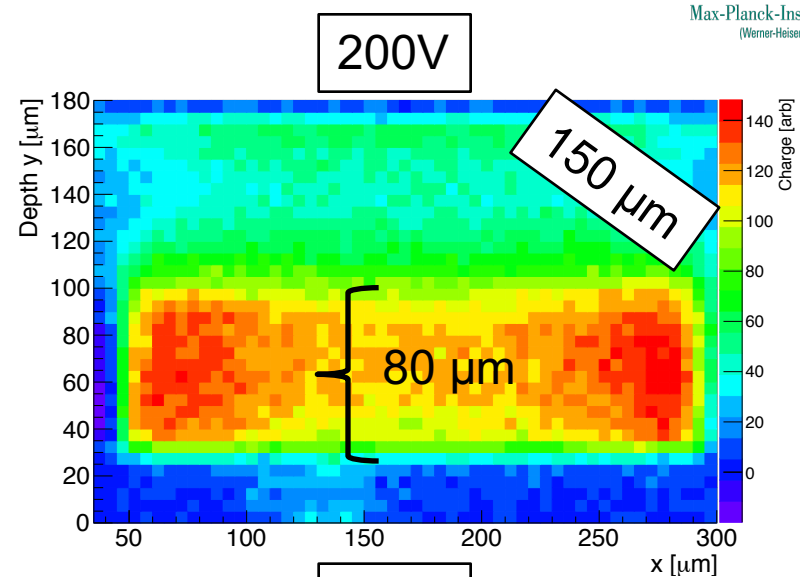
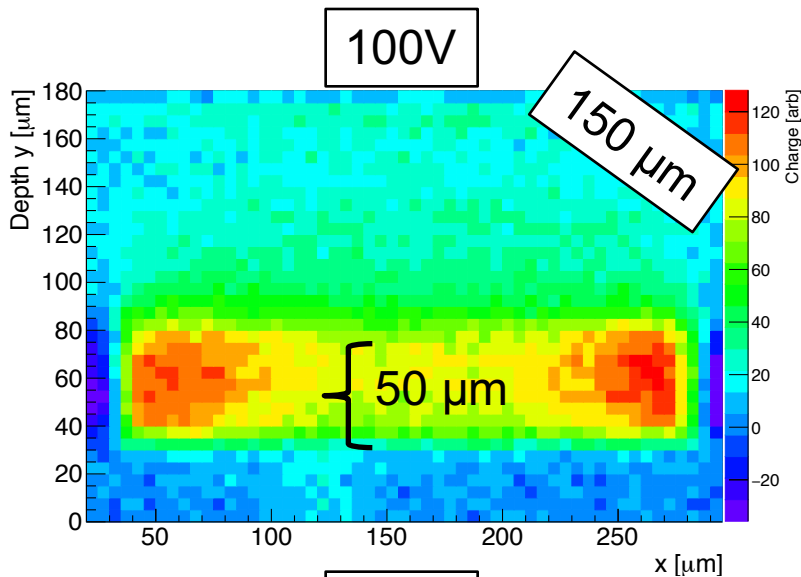


Irradiated to $5 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$

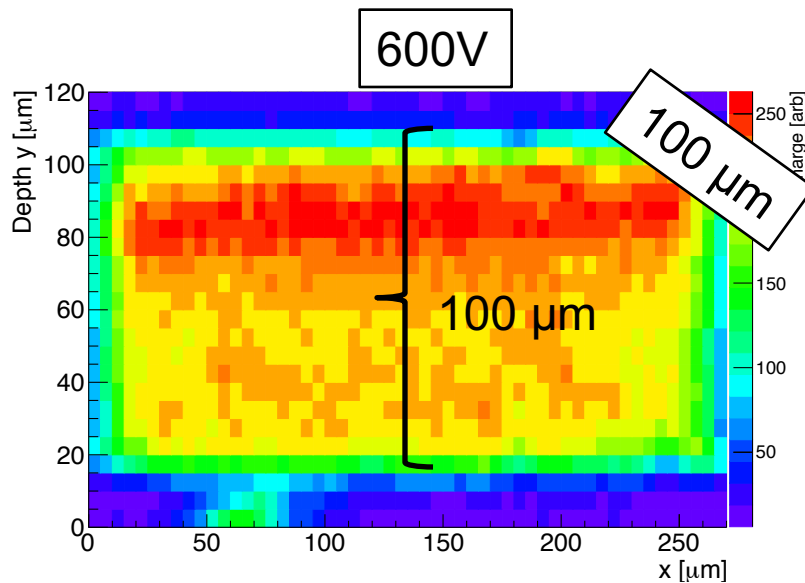
Depletion regions in 100 and 150 μm



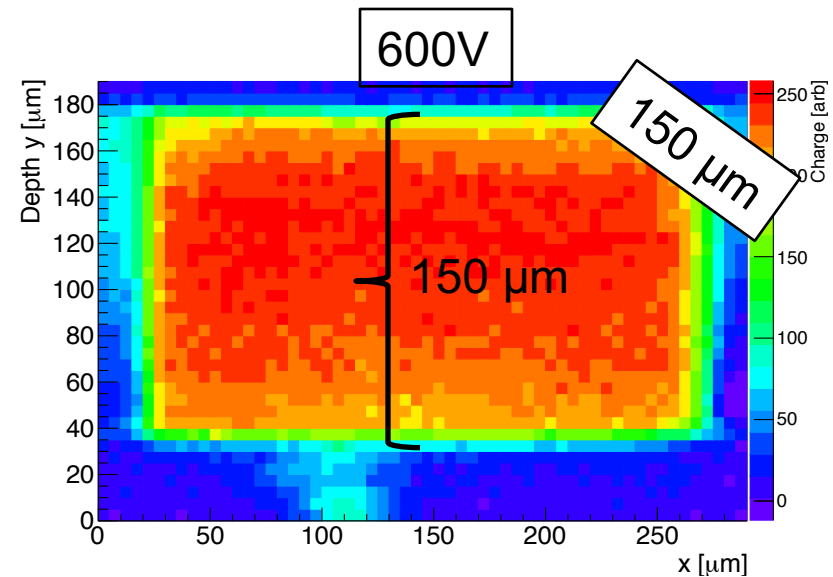
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Depletion regions in 100 and 150 μm



Depletion was at $\sim 300\text{V}$
(fully over depleted at 600V)



Depletion was at $\sim 500\text{V}$
(slightly over depleted)

- Depletion depths are only slightly larger for the $100\ \mu\text{m}$ sensor up 300V (depletion voltage of $100\ \mu\text{m}$ thick sensor)
- From 300V on the depletion depth of the $150\ \mu\text{m}$ thick sensor starts to get larger than the one of the $100\ \mu\text{m}$ thick sensor (depletion depth limited by the thickness)

Irradiated to
 $5 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$

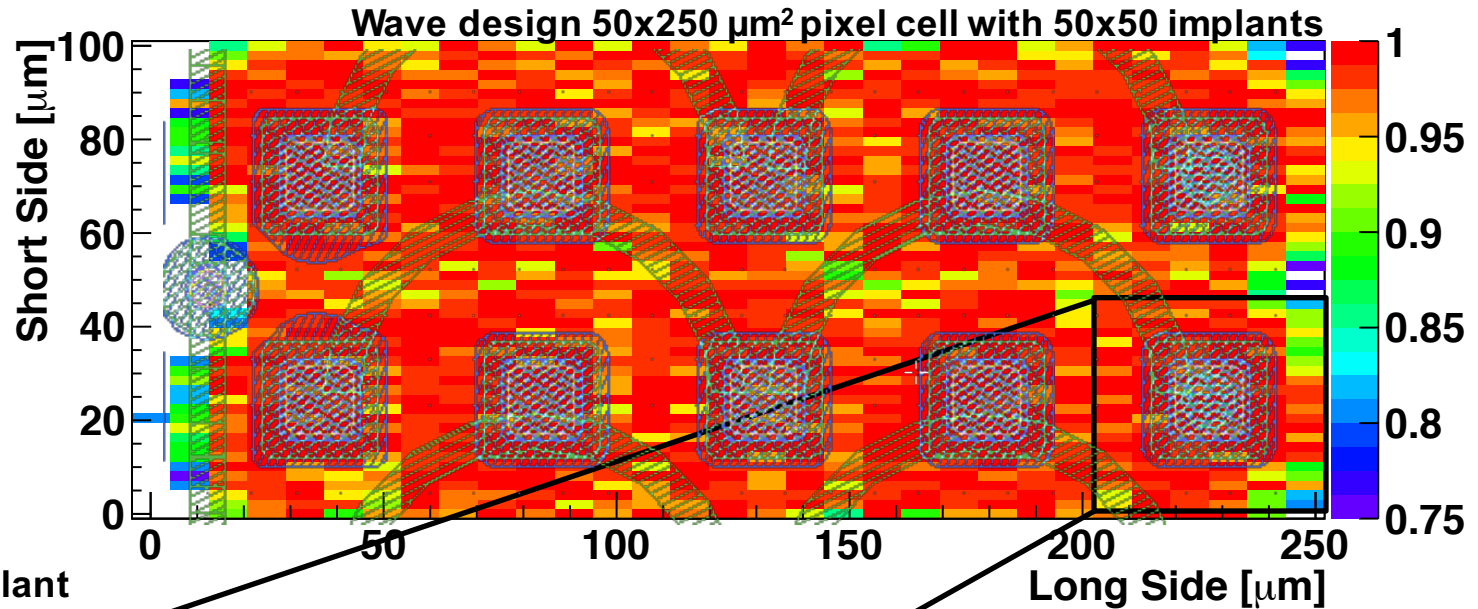
In-pixel efficiency at $3 \times 10^{15} n_{eq}/cm^2$

150 μm

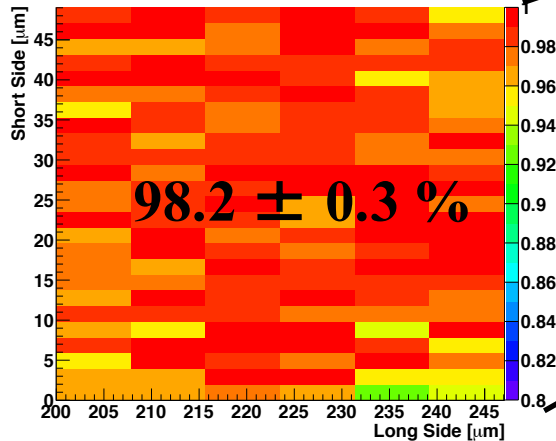


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Test beam results



50x50 implant



In-pixel efficiency of the 50x50 μm^2 implant (implant at the edge) is 98.2% when considering neighboring pixel implants read out by different read-out channels. Efficiency loss due to charge sharing.

Irradiated to
 $3 \times 10^{15} n_{eq}/cm^2$

In-pixel efficiency (irradiated to $3 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$)

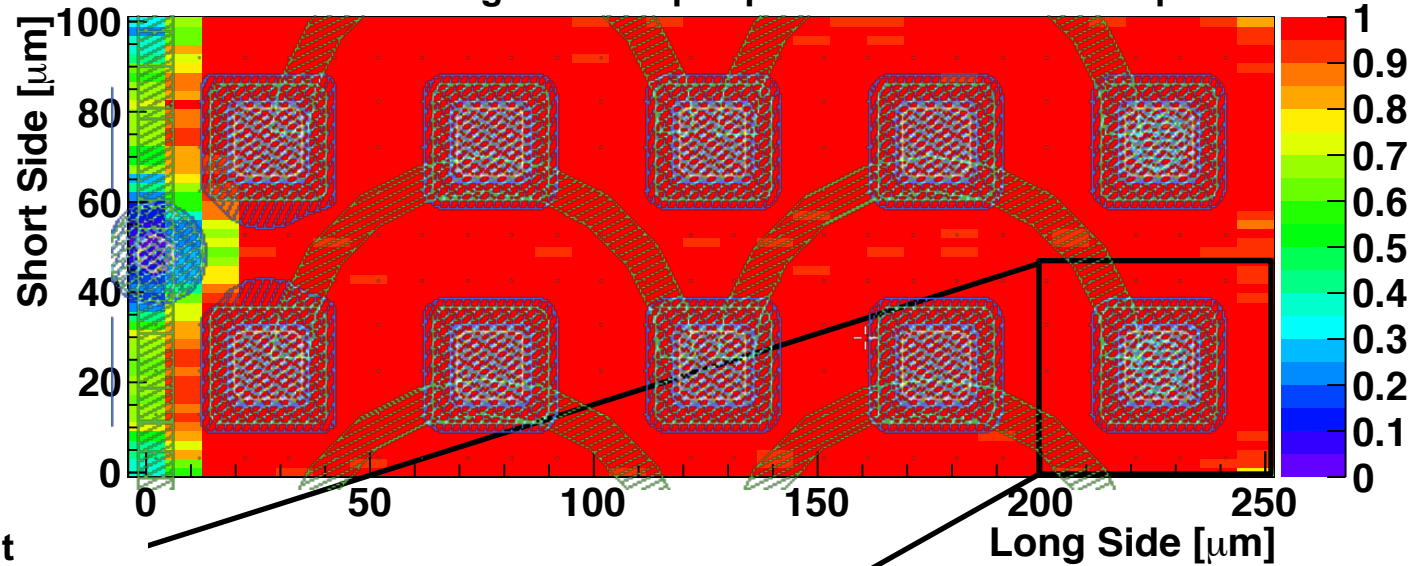
150 μm



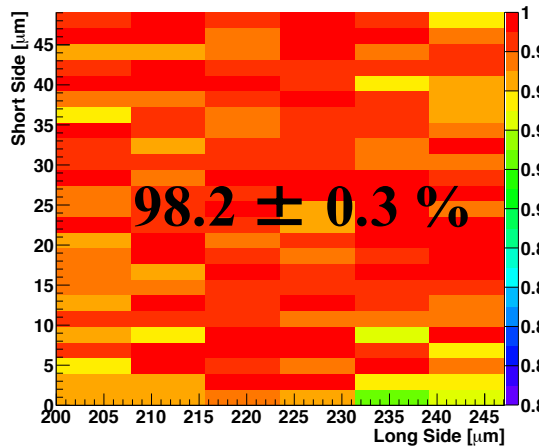
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Test beam results

Wave design $50 \times 250 \mu\text{m}^2$ pixel cell with 50×50 implants



50x50 implant



Irradiated to $3 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$